

Title (en)  
DEVICE FOR TREATING SUBSTRATES

Title (de)  
VORRICHTUNG ZUM BEHANDELN VON SUBSTRATEN

Title (fr)  
DISPOSITIF DE TRAITEMENT DE SUBSTRATS

Publication  
**EP 1161765 A1 20011212 (DE)**

Application  
**EP 00918768 A 20000308**

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Abstract (en)  
[origin: DE19911084A1] The invention relates to a device for treating substrates, especially semiconductor wafers, with at least one processing container that is provided with an opening which can be closed from the exterior during the treatment with the substrate. The aim of the invention is to provide a simple and homogeneous treatment of a surface pertaining to a substrate. The aim of the invention is also to reduce the danger of damage between successive treatment steps. To this end, a second processing container is provided adjacent to the first processing container. The wall of said second processing container is at least partially the container wall of the first processing container, whereby said container wall is provided with the opening which can be closed from the side of the first processing container.

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**H01L 21/00; C25D 7/12**

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AT DE

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